

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 2mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
L-934EW/1LYD	Yellow (GaAsP/GaP)	Yellow Diffused	0.7	1.5	40°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.
3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Yellow	590		nm	I _F =2mA
λ _D [1]	Dominant Wavelength	Yellow	588		nm	I _F =2mA
Δλ _{1/2}	Spectral Line Half-width	Yellow	35		nm	I _F =2mA
C	Capacitance	Yellow	20		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Yellow	1.85	2.5	V	I _F =2mA
I _R	Reverse Current	Yellow		10	uA	V _R = 5V

Notes:

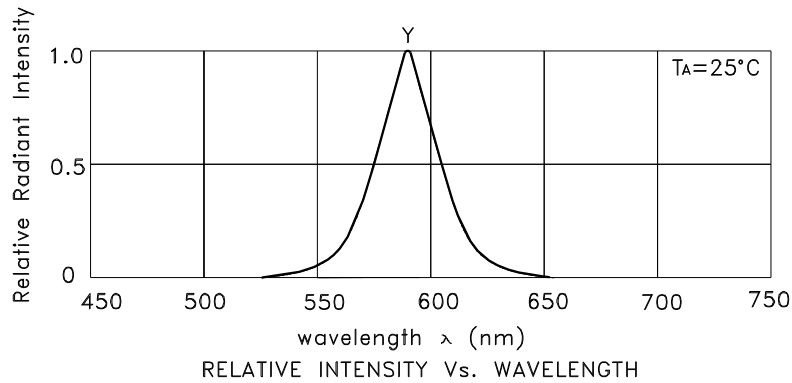
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Yellow	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [2]	260°C For 3 Seconds	
Lead Solder Temperature [3]	260°C For 5 Seconds	

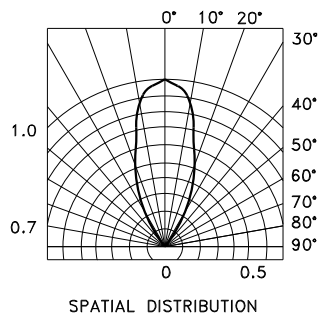
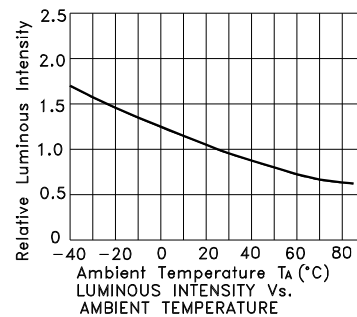
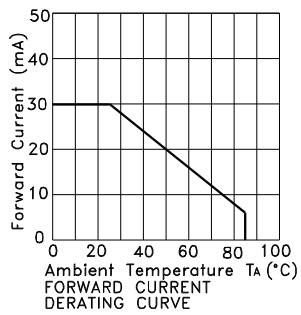
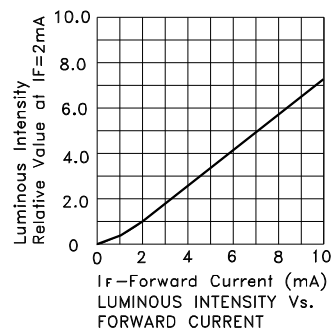
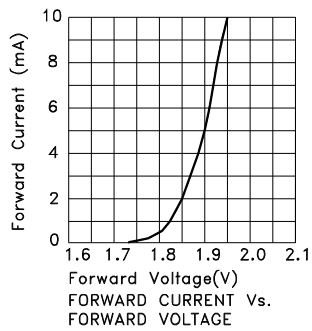
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.



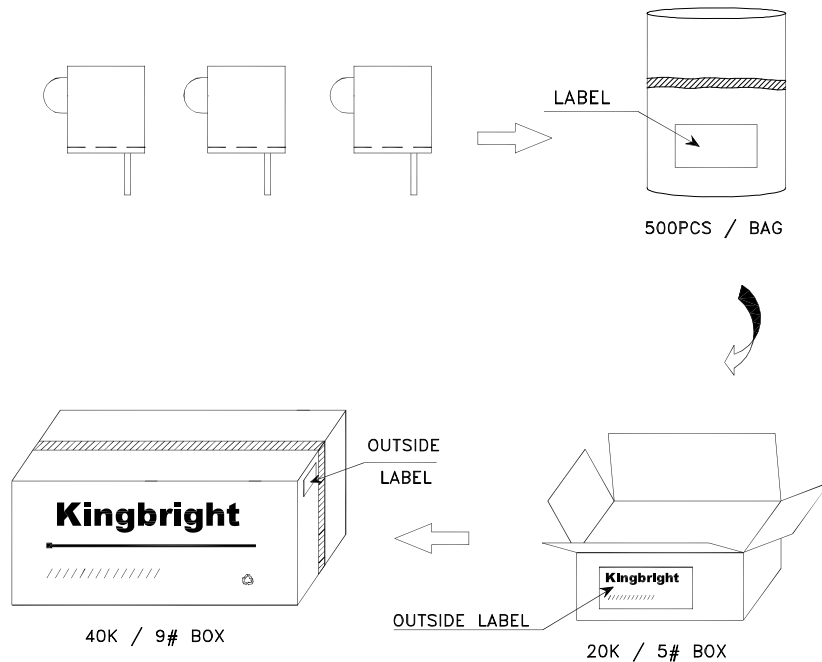
Yellow


L-934EW/1LYD



PACKING & LABEL SPECIFICATIONS

L-934EW/1LYD



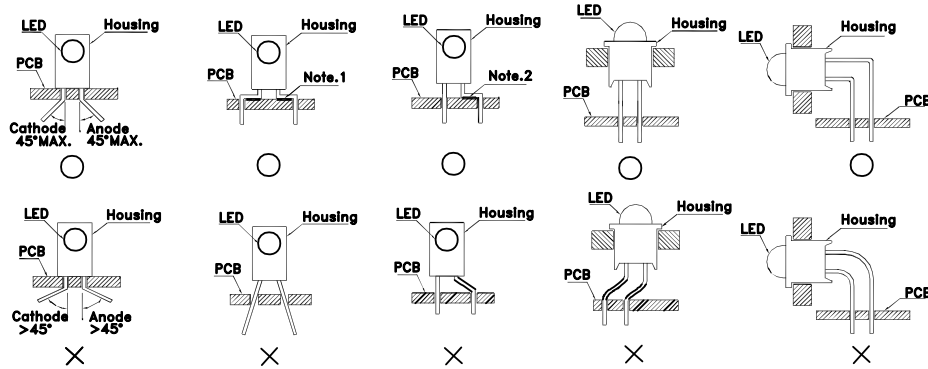
Kingbright	
P/NO: L-934EWxxx	
QTY: 500 pcs	Q.C. Q C XX XX XXXX PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
 <small>xxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxx</small>	
RoHS Compliant	

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PRECAUTIONS

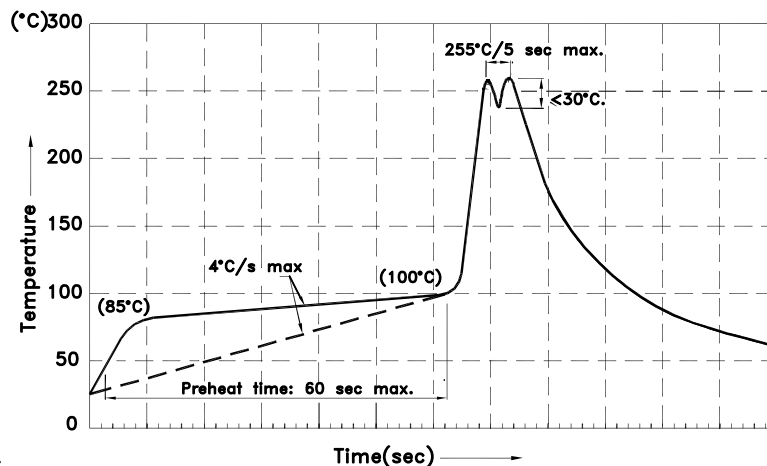
- The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



- During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- The tip of the soldering iron should never touch the lens epoxy.
- Through-hole LEDs are incompatible with reflow soldering.
- If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- Recommended Wave Soldering Profiles:



Notes:

- Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
- Do not apply stress to the epoxy resin while the temperature is above 85°C.
- Fixtures should not incur stress on the component when mounting and during soldering process.
- SAC 305 solder alloy is recommended.
- No more than one wave soldering pass.